阅读申明

1.本站收集的数据手册和产品资料都来自互联网，版权归原作者所有。如读者和版权方有任何异议请及时告之，我们将妥善解决。
2.本站提供的中文数据手册是英文数据手册的中文翻译，其目的是协助用户阅读，该译文无法自动跟随原稿更新，同时也可能存在翻译上的不当。建议读者以英文原稿为参考以便获得更精准的信息。
3.本站提供的产品资料，来自厂商的技术支持或者使用者的心得体会等，其内容可能存在描叙上的差异，建议读者做出适当判断。
4.如需与我们联系，请发邮件到marketing@iczoom.com，主题请标有“数据手册”字样。

Read Statement

ICZoom 拍明芯城

1. The datasheets and other product information on the site are all from network reference or other public materials, and the copyright belongs to the original author and original published source. If readers and copyright owners have any objections, please contact us and we will deal with it in a timely manner.

2. The Chinese datasheets provided on the website is a Chinese translation of the English datasheets. Its purpose is for reader’s learning exchange only and do not involve commercial purposes. The translation cannot be automatically updated with the original manuscript, and there may also be improper translations. Readers are advised to use the English manuscript as a reference for more accurate information.

3. All product information provided on the website refer to solutions from manufacturers’ technical support or users the contents may have differences in description, and readers are advised to take the original article as the standard.

4. If you have any questions, please contact us at marketing@iczoom.com and mark the subject with “Datasheets”.

Downloaded from www.iczoom.com

Final Product Change Notification 201309012F01

Issue Date: 07-May-2014
Effective Date: 05-Aug-2014

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

Change Category

[ ] Wafer Fab process	[ ] Assembly Process	[ ] Product Marking	[ ] Design
[ ] Wafer Fab materials	[X] Assembly Materials	[ ] Electrical spec./Test coverage	[ ] Mechanical Specification
[ ] Wafer Fab location	[ ] Assembly Location	[ ] Test Location	[ ] Packing/Shipping/Labeling

Change of bond wire from Au to Cu and release of 2nd source mold compound in SOT323

Details of this Change

Scheduled changes affect product types in SOT323 package only.
(1) The bond wire material will be changed from gold (Au) to copper (Cu). Implementation of change to copper wire as given by planned first shipment date below. Gold wire remains qualified for supply security reasons only.
(2) A second source mold compound supplier will be introduced for copper wire products.

Old product: wire material is Au (with currently used mold compound suppliers)
Changed product: wire material is Cu (with currently used first and new second source mold compound supplier) or Au (with currently used mold compound suppliers)

The design and materials of all other components will remain unchanged: die, die attach, and lead frame. Reliability qualification and full electrical characterization over temperature have been performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and with the same distribution).

Why do we Implement this Change

(1) Aligning with world technology standards, NXP continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.
(2) Following NXP company policy of second source material availability, a second source mold compound will be added to the BOM. The second source is already a well-established mold compound supplier for NXP GA discrete semiconductor products.

Identification of Affected Products

Changed products can be identified by date code after implementation.

Product Availability

Sample Information
Samples are available upon request
Latest sample request date for PCN samples is 10-Jun-2014.
Production
Planned first shipment 11-Aug-2014

Impact

No impact to the products' functionality anticipated.
Data Sheet Revision
No impact to existing datasheet
Disposition of Old Products
Existing inventory will be shipped until depleted

Related Notifications

Notification	Issue Date	Effective Date	Title
201003008F	26-Mar-2010		Change of bond wire material from gold to copper in SOT23 package
201005007F	27-Aug-2010		Change of bond wire material from gold to copper in SOT23 package
201204012F01	12-May-2012	10-Aug-2012	Change of bond wire material from gold to copper in SOT23 package
201309012A	21-Dec-2013		Change of bond wire from Au to Cu and release of 2nd source mold compound in SOT323

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 06-Jun-2014.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:
Name GA Customer Support
e-mail address DiscrQA.Helpdesk.GA-Products@nxp.com
At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

A global semiconductor company with operations in more than 25 countries, NXP posted unaudited revenue of $4.36 billion in 2012.

You have received this email because you are a designated contact or subscribed to NXP's Quallity Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

View Notification	Subscription	Support

NXP | Privacy Policy | Terms of Use

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2010 NXP Semiconductors. All rights reserved.